

2017 NXP-450 SELECTIVE SOLDERING SYSTEM





USA





Brazil

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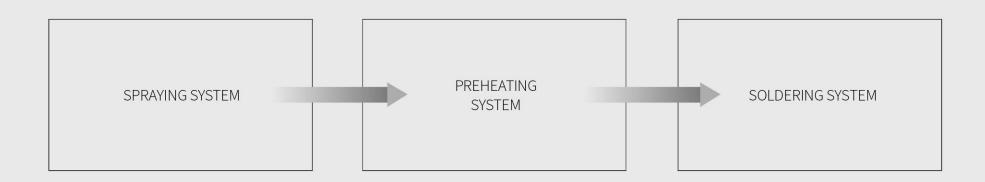


AUTOMATION, SMT & LEAN MANUFACTURING



Our Wave Soldering machine has ${\bf 3}$ systems:

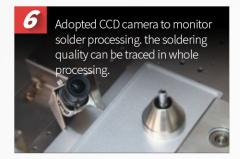
- Spraying System
- 2 Preheating System
- **3** Soldering System





- 1 High Accuracy
- 2 Stable and Reliable
- Production efficiency and easy maintenance
- 4 Available offline programming







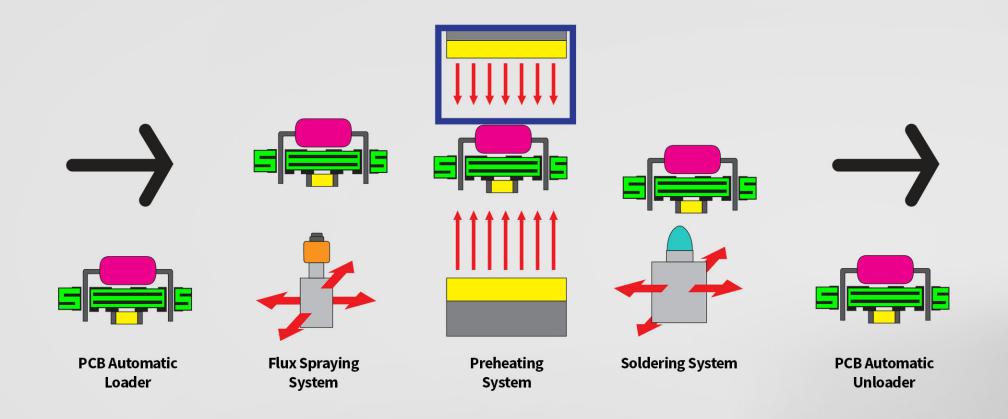




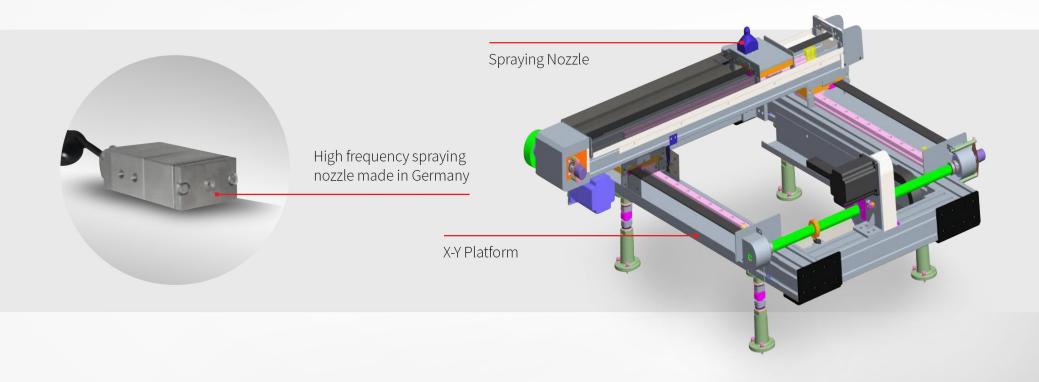
- Lead Free Acceptable
- Through-hole soldering flexibility; single point, drag, mini-wave, or dip soldering
- Production capacity and investment costs can be flexibly adapted to meet actual needs through this consistent modular design
- Precise axis system for accurately positioning the individual workstations
- Maximum flexibility with quick-change solder nozzles, wettable or non-wettable depending on your application
- Unbeatable price/ performance ratio



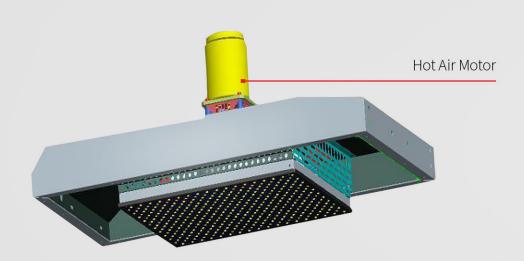




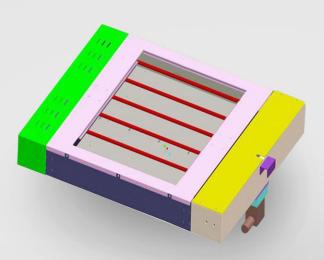
The flux spraying system adopts fixedness pressure stainless steel pot with filter device to drive the flux to the spraying nozzle. The high frequency spraying nozzle starts to work controlling by pulse signal. Flux is sprayed like a bullet. The flux consumption can be controlled accurately by pulse signal and width.



The temperature controls for top and bottom preheating is independent, Cs lamp heating can improve heating efficiency and temperature uniformity.

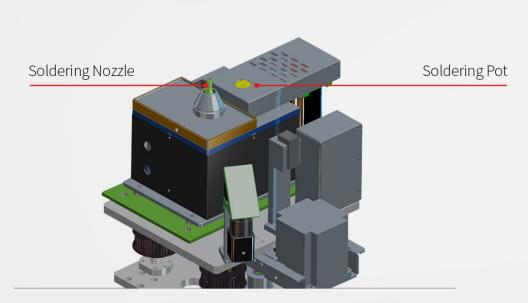


Top Preheating

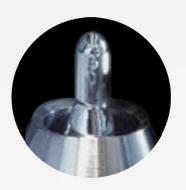


Bottom Preheating

The point soldering pot is drived to the position where is needed by X-Y-Z platform accurately. It can solder both single point and multi-point. The soldering nozzle can be made according to customer's requirement.



Point Soldering Module



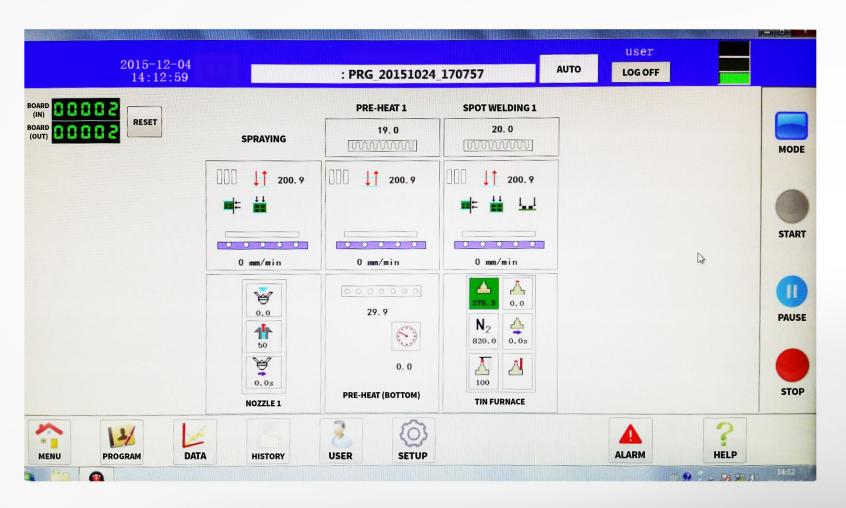
* Wave shape & spraying nozzle

Soldering Nozzle Adopted CCD camera to monitor solder processing, the soldering quality can be traced in whole processing.



Offline programming software is included and can be used either with Gerber or JPG's, inputting the x and y coordinates.

There is no need to interrupt production to make new programs.



Energy saving and environmental protection: Compared with the traditional wave soldering, our machine can save more energy and save you production costs.

COST COMPARISON SHEET

ltem	Traditional Wave Soldering	Our Selective Wave Soldering	Notice
Oxidized tin per hour	0.65kg	0.05kg	
Fluxed consumption per hour	0.6kg	0.03kg	
Nitrogen consumption per hour	24m ³	2m³	
Power consumption per hour	13KW	6KW	

^{*} We can get a conclusion: Selective wave soldering can save more cost of producing productions from the sheet.

SPECIFICATIONS NXP-450

ltems	Specification
Min. PCB Size	L 120mm x W 60mm
Max. PCB Size	L 550mm x W 450mm
PCB Thickness	0.5~6mm
PCB Weight	Max. 5kg
PCB Upper Space	Max. Upper 100mm
PCB Down Space	Bottom 50mm
PCB Process Edge	4mm
Board Handling System Conveyor System	2 independent sons with independent control she're and associal town plate
Conveyor System Conveyor Height	3 independent zone with independent control, chain and special turn plate 850+/-50mm
Width Adjustment	60mm to 460mm
Width Adjustment Accuracy	+/-0.2mm
Conveyor Direction	Left to right / right to left
Preheating System - Bottom Side	Mar. 1008 C /DCD and and /Mar. 101a.
Pre-heating Temperature / Power Temperature Control Accuracy	Max. 160 ° C (PCB surface)/ Max.18kw
Heater	+/-2°C @3 sigma / Cpk≥1.33
Heating Area	Philips Cesium light, Independent control L 650mm x 580mm
Preheating System - Top Side	L 050HIII X 360HIII
Preheating System - Top side Preheating Temperature / Power	Max. 160° C (PCB surface)/ Max.8kw
Temperature Control Accuracy	+/-2°C @3 sigma / Cpk≥1.33
Heater	Hot air, Independent Control
Fluxing System	not all, illueperident Control
Fluxer Nozzle	Micro drop jet fluxer
Fluxing Wet Area	Ø2 mm to Ø5mm
Flux Types	Alcohol or Water based
Fluxing Controller	Automatic level control with capacitive sensor
Selective Position Method	X-Y Platform
Position Speed / Accuracy	Max.400mm/s , +/-0.25mm
Flux Container	3L pressure tank
Soldering Unit for Soldering Processes	
Solder pot compatible for Lead-Free Soldering	Standard
Nitrogen Operation	Standard
Automatic Wave Height and Solder Level Control	Standard
Automatic Wire Solder Feeder	Standard
Wettable and Non-Wettable quick change nozzles	Standard
Solder Bath Temperature	300°C
Temperature Control Accuracy	+/-2°C @3 sigma / Cpk≥1.33
Solder Pot Capacity	12kg lead free
Wave Height	Max. 5mm
Solder Pot moving speed	Max. 400mm/s
Soldering Nozzle Dimensions	Ø5 to Ø12mm (or customized)
Control System	
Power Supply	380VAC, 3 P, 50 / 60Hz, 52A
PCB Data Import	GERB file, Offline file import, Image program
Programming Interface	Windows Interface
Power	35kw

